



Material Content Data Sheet



Sales Product Name		ICB2FL03G		Issued		24. January 2018		
MA#		MA001235636						
Package		PG-DSO-16-23		Weight*		153.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.766	1.80	1.80	17965	17965
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.066	0.04		426	
	non noble metal	iron	7439-89-6	1.311	0.85		8517	
wire	non noble metal	copper	7440-50-8	53.247	34.58	35.48	345815	354864
	noble metal	gold	7440-57-5	0.358	0.23	0.23	2325	2325
	encapsulation	organic material	carbon black	1333-86-4	0.281	0.18		1822
plastics		epoxy resin	-	9.072	5.89		58922	
	inorganic material	silicondioxide	60676-86-0	84.177	54.68	60.75	546694	607438
leadfinish	non noble metal	tin	7440-31-5	1.530	0.99	0.99	9938	9938
plating	noble metal	silver	7440-22-4	0.226	0.15	0.15	1466	1466
glue	plastics	acrylic resin	-	0.203	0.13		1321	
	noble metal	silver	7440-22-4	0.721	0.47	0.60	4683	6004
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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